Supplier Name: Contact Info: Form/Declaration Type: Created on:

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

Distribute - RoHS and IEC 06/02/2022

Details for "LP2951-50QDRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LP2951-50QDRQ1	NIPDAU	Level-3-260C-168 HR	TI AGUASCALIENTES	D 8	4.9x3.9x1.75	108.2

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

		CAS Number		Homogeneous Material Level		Component Level	
Component	Substance		Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.084688	100	1000000	0.078252	783
Sub-Total			0.084688	100	1000000	0.078252	783
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.182519	78.9999	789999	0.168648	1686
Thermoplastics	Ероху	85954-11-6	0.048518	21.0001	210001	0.044831	448
Sub-Total			0.231037	100	1000000	0.213479	2135
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	45.310704	97.05	970500	41.867187	418672
Copper and Its Alloys	Iron	7439-89-6	1.213888	2.6	26000	1.121635	11216
Copper and Its Alloys	Phosphorus	7723-14-0	0.070032	0.15	1500	0.06471	647
Zinc and Its Alloys	Zinc	7440-66-6	0.093376	0.2	2000	0.08628	863
Sub-Total			46.688	100	1000000	43.139811	431398
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.154094	95.119753	951198	0.142383	1424
Precious Metals	Gold	7440-57-5	0.001264	0.780247	7802	0.001168	12
Precious Metals	Palladium	7440-05-3	0.006642	4.1	41000	0.006137	61
Sub-Total			0.162	100	1000000	0.149688	1497
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	52.992693	88	880000	48.965361	489654
Other Plastics and Rubber	Carbon Black	1333-86-4	0.180657	0.3	3000	0.166927	1669
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.331204	0.549999	5500	0.306033	3060
Thermoplastics	Ероху	85954-11-6	6.714415	11.15	111500	6.204134	62041
Sub-Total			60.218969	100	1000000	55.642455	556425
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.840165	100	1000000	0.776314	7763
Sub-Total			0.840165	100	1000000	0.776314	7763
Total			108 224850			100	1000000
iutai			108.224859			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/02/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GASI and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.